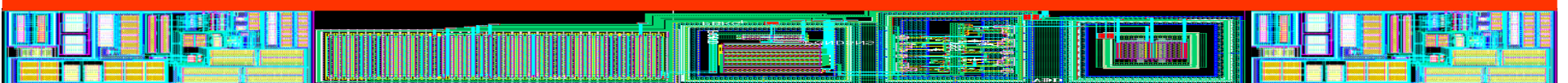
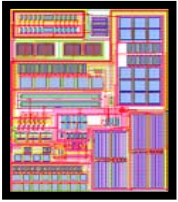


EE6326 Analog IC Design - Fall 2008

HW#3 Design Guide

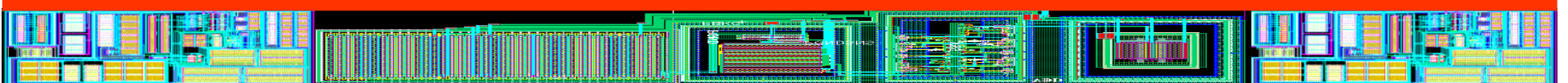
Wenliang Chen, Ph. D.
Instructor

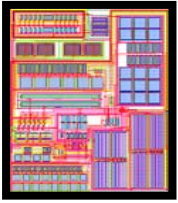




Outlines

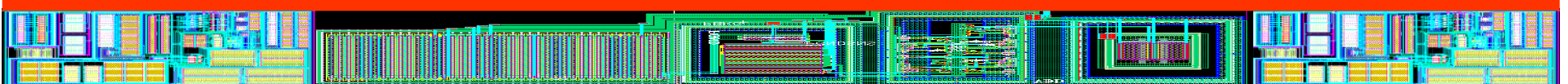
- This design guide and class-note-05 are needed as references to complete HW#3.
- Design Blocks
 - Brokaw Bandgap
(architecture can be different.)
 - Constant current references & mirrors
 - IPTAT current references & mirrors
 - Constant G_m current references & mirrors
 - Thermal shut down circuit

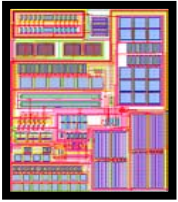




Design Steps

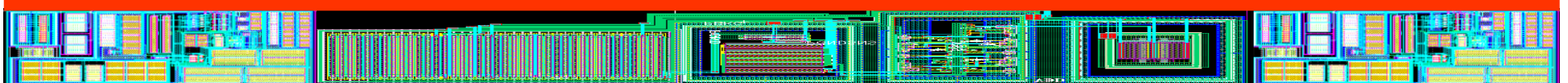
- **Design a bandgap circuit containing IPTATxR and VBE parts**
 - The IPTAT part will be re-used as current reference
 - A start-up circuit is needed
- **Design a constant current reference and mirror**
 - An ideal OPAMP is approximated with a "vcvs" ideal voltage source in cadence.
 - VBG and an external zero T.C. R are used to generate constant currents
 - Both current sources and current sinks are required.
- **Design an IPTAT current reference and mirror**
 - Re-use it from BG circuit
 - Only current sources are needed
- **Design a constant G_m current reference and mirrors**
 - An ideal OPAMP and VBG are used to increase R_{out}
 - Only current sinks are needed.
- **Design a thermal shut down circuit**
 - $T_{z,h}=150C$ & $T_{z,l}=130C$
 - Thermal hysteresis of 20C is achieved by changing sensing-R values.

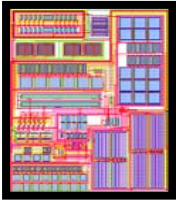




BJT model setup

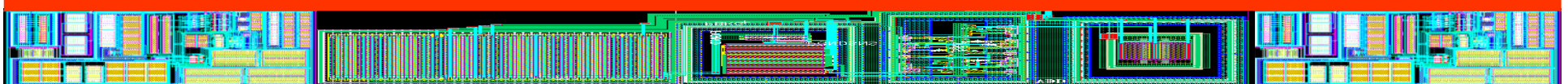
- In your UNIX home directory, please make a directory called "models".
- Copy "NPN_AE13" into the "models" directory
- To add a BJT symbol into your schematic
 - "i" → "NCSU_Analog_parts" → "N_Transistors" → "npn" → drag it to a desired spot in your schematic then left click → key in "NPN_AE13" in the Model name and Multiplier number
 - In case changes of NPN_AE13 BJTs are needed, please "Q" the BJT symbol and type in "numbers of BJTs" in the "Multiplier" cell.
- When you are ready to run simulations, please include this model in ADE's model libraries path:
 - In "ADE" simulation window → setup → Model Libraries → key in "~/models/NPN_AE13" → Hit "O.K."



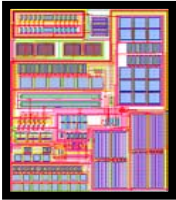


Adding a BJT into your schematic

The screenshot displays two overlapping windows from a circuit design software. The 'Component Browser' window on the left shows a tree view of components under the 'NCSU_Analog_Parts' library. The 'Add Instance' dialog box on the right is open, showing the configuration for adding a component. The 'Library' is set to 'NCSU_Analog_Parts', the 'Cell' is 'npn', and the 'View' is 'symbol'. The 'Model name' is 'NPN_AE1'. The 'Multiplier' is set to '2'. The 'Array' section shows 'Rows' and 'Columns' both set to '1'. The 'Device area' is empty. The 'Temp rise from ambient' is also empty. The 'Bulk node connection' is empty. The 'Rotate', 'Sideways', and 'Upside Down' buttons are visible. The background shows a schematic diagram with a transistor symbol.



Adding NPN AE13 into Model Libraries Path!



Cadence® Analog Design Environment (1)
 Status: Ready T=27.0 C Simulator: spectre 4

Session Setup Analyses Variables Outputs Simulation Results Tools Help

Design ...
 Simulator/Directory/Host ...
Library E Model Libraries ...
 Temperature ...
 Cell H Stimuli ...
 View s Simulation Files ...
 Environment ...
 Design variables

Analyses

Arguments.....	Enable
t	yes
0 10m	yes

Outputs

#	Name	Value	#	Name/Signal/Expr	Value	Plot	Save	March
1	VG	2.38	44	net0367		no	allv	no
2	VDP	2.8	45	P39/D		no	yes	no
3	VDN	1.5	46	N25/D		no	yes	no
4	felk	3K	47	N26/D		no	yes	no
5	VOUT	1	48	N24/D		no	yes	no
			49	N27/D		no	yes	no

make a directory called
 directory

- When you are ready to run simulations, please include this m...
 in ADE...
 - In "

spectre0: Model Library Setup

OK Cancel Defaults Apply Help

#Disable|Model Library File Section

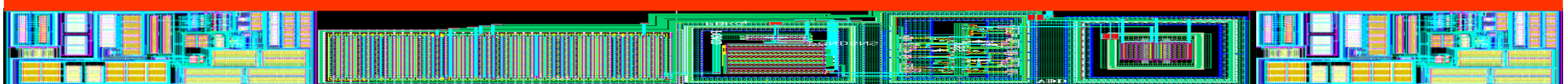
... cad/ee6326/ncsul.3/local/models/spectre/nom/tsmc35N.m.n88y	Enable
... cad/ee6326/ncsul.3/local/models/spectre/nom/tsmc35P.m.n88y	Disable

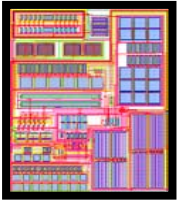
Up Down

Model Library File Section (opt.)

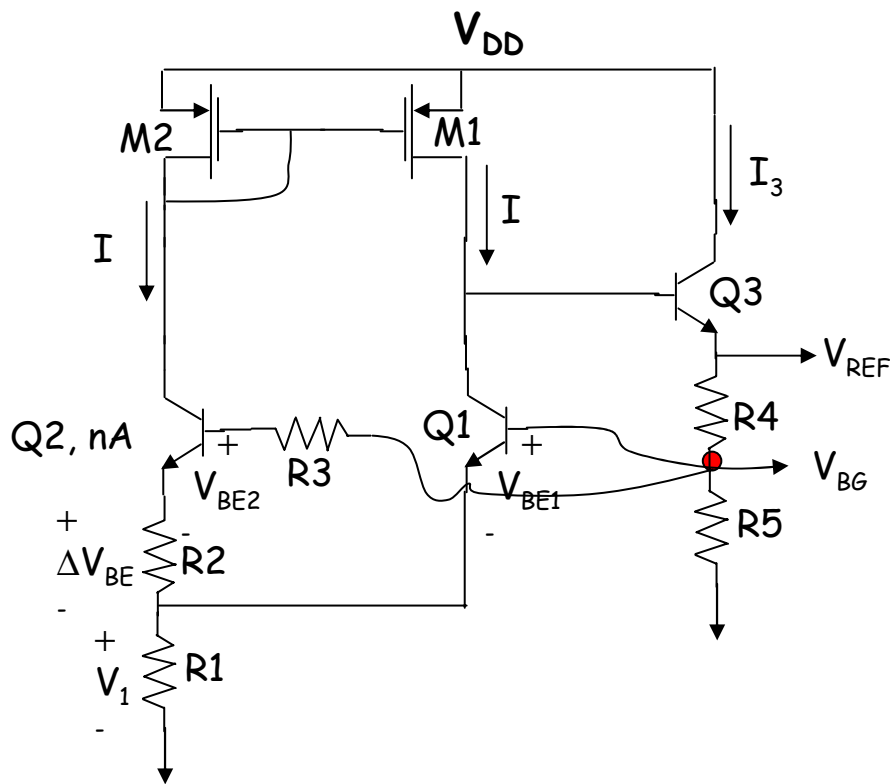
~/models/NPN_AE13

Add Delete Change Edit File Browse...





Brokaw Bandgap



$$V_{BG} = V_1 + V_{BE1}$$

$$= 2 \times I \times R_1 + V_{BE1}$$

$$I = \frac{\Delta V_{BE}}{R_2} = \frac{V_T \ln(n)}{R_2}$$

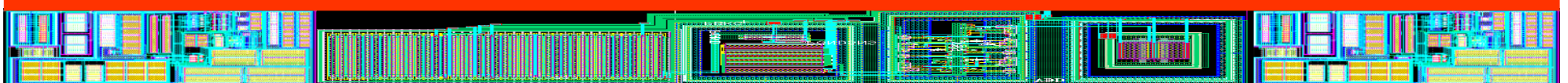
$$V_{BG} = \frac{2 \times R_1}{R_2} V_T \ln(n) + V_{BE1}$$

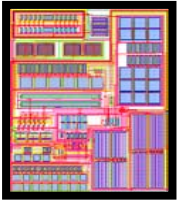
$$= k_b \times V_T + V_{BE1}$$

$$V_{ref} = V_{BG} \left(1 + \frac{R_4}{R_5}\right)$$

R_3 is to keep $V_{BE1} = V_{BE2}$

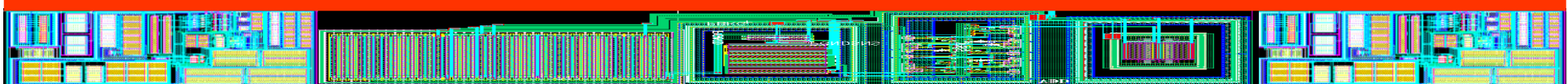
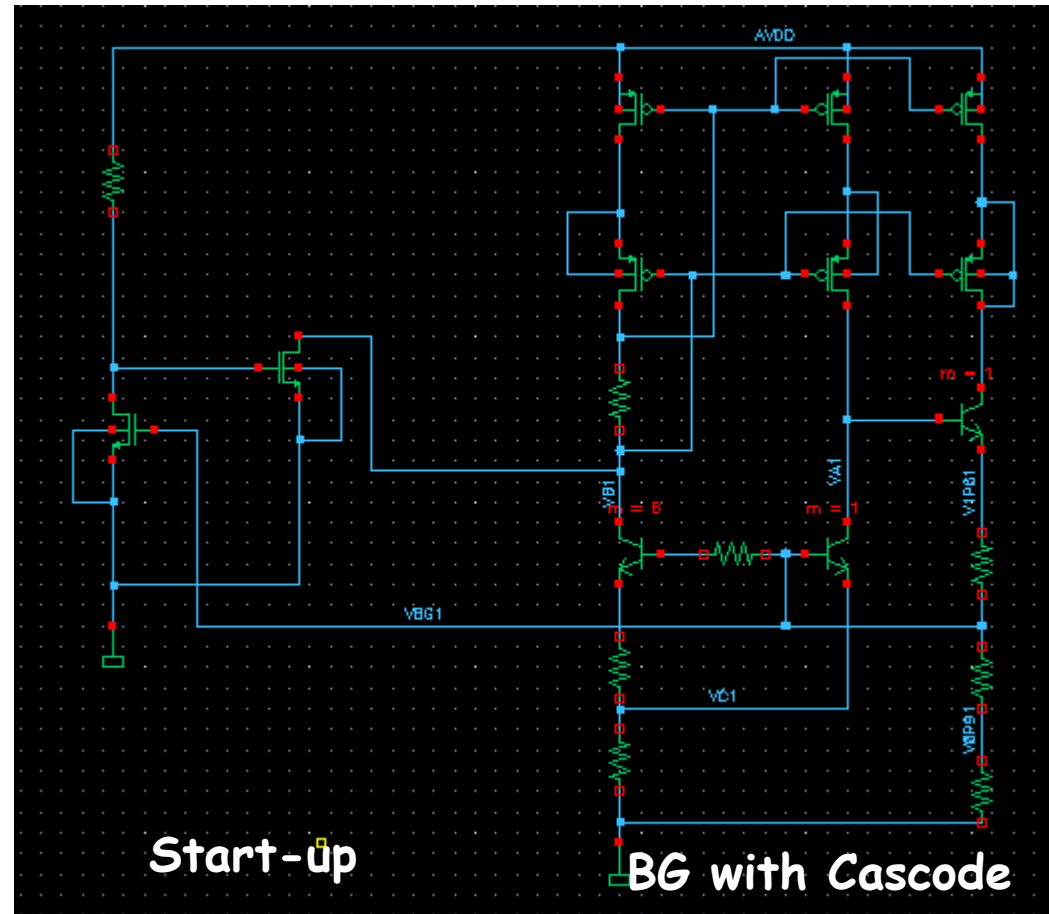
$$R_3 \sim \frac{R_2}{R_1} \left(\frac{R_4 R_5}{R_4 + R_5} \right)$$

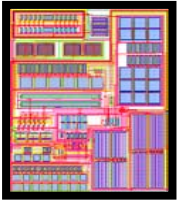




Brokaw Bandgap

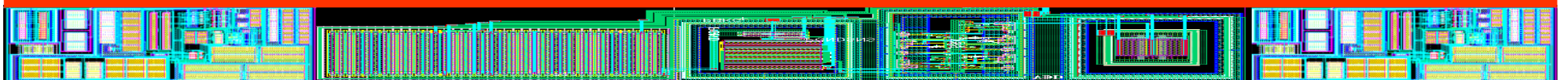
UTD models

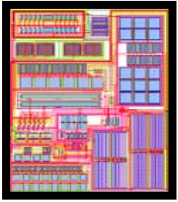




Design Procedure of Brokaw BG for VBG

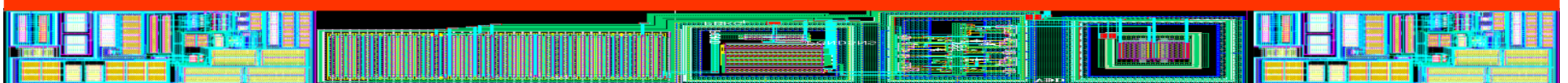
- Specification: $V_{BG}=1.2V$, $V_{ref}=1.6V$, $I=10\mu A$, $I_3=10\mu A$
- Let's assume a n first & room temp = 300K
- $I = VT \ln(n)/R_2 \rightarrow R_2 = VT \ln(n)/I$
- Since $V_{BG}=1.2V$, $V_{BG} = 2IR_1 + V_{BE1} = 20e^{-6} \times R_1 + V_{BE1} = 1.2$
- Let's assume $V_{BE}=0.7V$, $\rightarrow R_1 = (1.2 - 0.7) / 2I$
- $I_3 = V_{BG}/R_5$, $\rightarrow R_5 = 1.2/I_3$
- $V_{ref} = V_{BG}(1 + R_4/R_5)$, $R_4 = (V_{ref}/V_{BG} - 1) \times R_5$
- $R_3 = (R_2/R_1) [R_4 R_5 / (R_4 + R_5)]$
- Make sure that the choice of PMOS are in saturation region & BJT are in active region
- If hand-calculation does not match sim. results, please adjust R_1 , R_2 & R_3 and iterations.
- For DC accuracy, adjusting R_1 & R_2 are crucial.

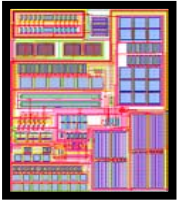




Design procedure of Brokaw BG for PSRR

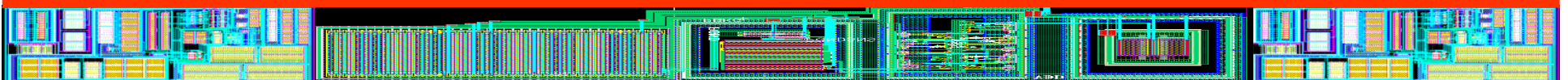
- Target PSRR=40dB, $I=10\mu\text{A}$, $I_3=10\mu\text{A}$
- $\text{PSRR}=20\log(\Delta\text{VBG}/\Delta\text{Vnoise@supply})$
- Let's plan to use PMOS $2\Delta V_{\text{OD}}$ wide-swing cascode on top Brokaw BG to provide the 40dB PSRR. The question is how does PSRR spec. translates to the required output impedance?
- If R_{out} is larger, ΔI is smaller.
- $\text{VBG}=2\times I\times R_1+V_{\text{BE1}}$; $\Delta\text{VBG}=2\Delta I\times R_1$, assuming V_{BE1} remains unchanged.
- Reasonable $\Delta\text{Vnoise@supply}\sim 100\text{mV}$ thus $\Delta\text{VBG}=1\text{mV}$.
- $R_1\sim 25\text{ K}\Omega$, thus $\Delta I=\Delta\text{VBG}/2R_1=1\text{mV}/50\text{ K}\Omega=20\text{nA}$
- $R_{\text{out_min}} > \Delta\text{Vnoise@supply}/20\text{nA} = 100\text{mV}/20\text{nA} = 5\text{M}\Omega !$

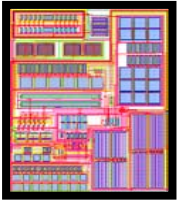




Design procedure for R_{out} of Wide-swing Cascode current mirror

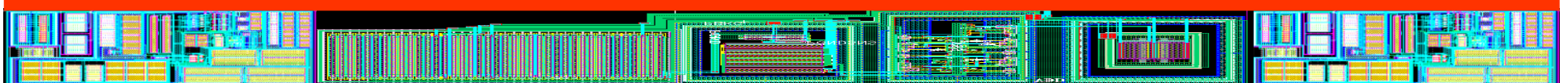
- $R_{out} \sim g_{m2} \times r_{ds2} \times r_{ds1}$; $g_{m2} = 2I_D / V_{GS_T}$
Thus $R_{out} \sim (2I_D / V_{GS_T}) r_{ds}^2$
- Assume $V_{GS_T} \sim 200\text{mV}$; $I_D = 10\mu\text{A}$; $g_{m2} \sim 2e-5 / 0.1 = 2e-4 = 100\mu\text{S}$
- $R_{out} = 5e6 = 1e-4 \times r_{ds}^2 \rightarrow r_{ds} > 224\text{k}\Omega$
- We also know the potential of base of Q3 $\sim 1.6\text{V} + 0.7\text{V} = 2.3\text{V}$
- Thus the V_{out} of the PMOS $2\Delta V_{OD}$ wide-swing cascode is 2.3V
- The $2\Delta V_{OD} \sim 1\text{V}$, assume equal split $\Delta V_{OD} \sim 0.5\text{V}$.
- Thus the design spec. of output stage of PMOS $2\Delta V_{OD}$ wide-swing cascode is as following:
 - $I_D \sim 10\mu\text{A}$; One $\Delta V_{OD} \sim 0.5\text{V}$, $AV_{DD} = 3.3\text{V}$ & $V_{out} \sim 2.3\text{V}$.
 - $r_{ds} > 224\text{k}\Omega$; $V_{GS_T} \sim 200\text{mV}$; $g_{m2} \sim 100\mu\text{S}$
- Choose PMOS's size
 - dc OP sim. to get $|V_{th,p}| \sim 740\text{mV}$
 - Sweep I-V curve of PMOS such that
 - $I_D \sim 10\mu\text{A}$, $\Delta V_{OD} \sim 0.5\text{V}$, $r_{ds} > 224\text{k}\Omega$, $|V_{GS_T}| \sim 200\text{mV}$ & $g_{m2} \sim 100\mu\text{S}$
 - Rough estimate size $\sim 4(2.5/1)$

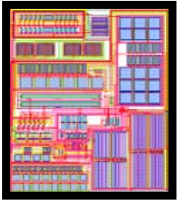




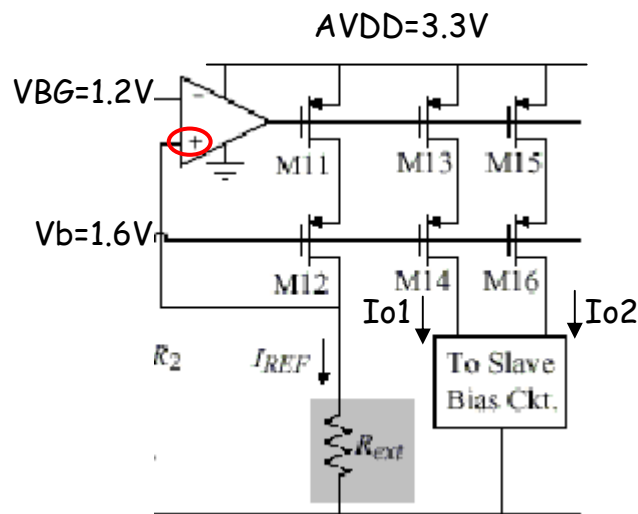
Testing of Brokaw BG

- T.C.:
 - Use dc analysis, sweep temp. from -40C to 125C
 - Use calculator function VS(VBG) to get VBG vs temp plot
 - T.C. = $\Delta VBG / 1.2V / 165C \times 1e6$ (ppm/°C)
- PSRR:
 - Use "vsin" source to add noise with 0.1V amplitude
 - Offset voltage=0V
 - Amplitude=100mV
 - Frequency=1KHz
 - DC voltage=0V
 - Run transient analysis for 10ms
 - Plot VBG vs time
 - Measure the amplitude of VBG_{pk-pk}
 - PSRR = $20 \times \log (\Delta VBG_{pk-pk} / 0.2)$ in dB

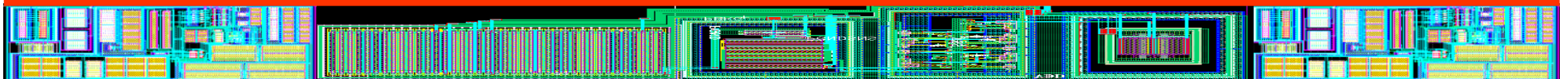


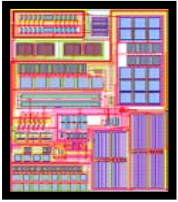


Constant Current Reference & Mirror



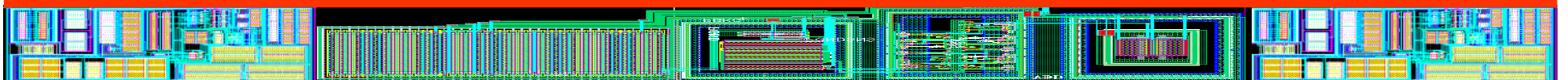
- 1) Use VBG to generate constant current reference
- 2) $I_{ref}=1\mu A$, $R_{ext}=V_{BG}/I_{ref}$
(this R_{ext} is too big for good noise performance, we will discuss noise and current trade off later.)
- 3) If $(W/L)_{14}=(W/L)_{12}$ & $(W/L)_{13}=(W/L)_{11}$ then $I_{O1}=1\mu A$
- 4) If $(W/L)_{16}=10(W/L)_{12}$ & $(W/L)_{15}=10(W/L)_{11}$ then $I_{O2}=10\mu A$
- 5) Use wide-swing cascode to generate current sinks of $5\mu A$ & $500nA$
- 6) Rout measurements:
 - a. Connect a dc voltage source at the output of current sinks or current sources.
 - b. Set the dc voltage to 1V, measure I_{out1}
 - c. Set the dc voltage to 2V, measure I_{out2}
 - d. $R_{out} \sim 1/|I_{out1}-I_{out2}|$

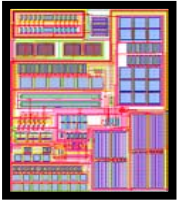




IPTAT reference and mirrors

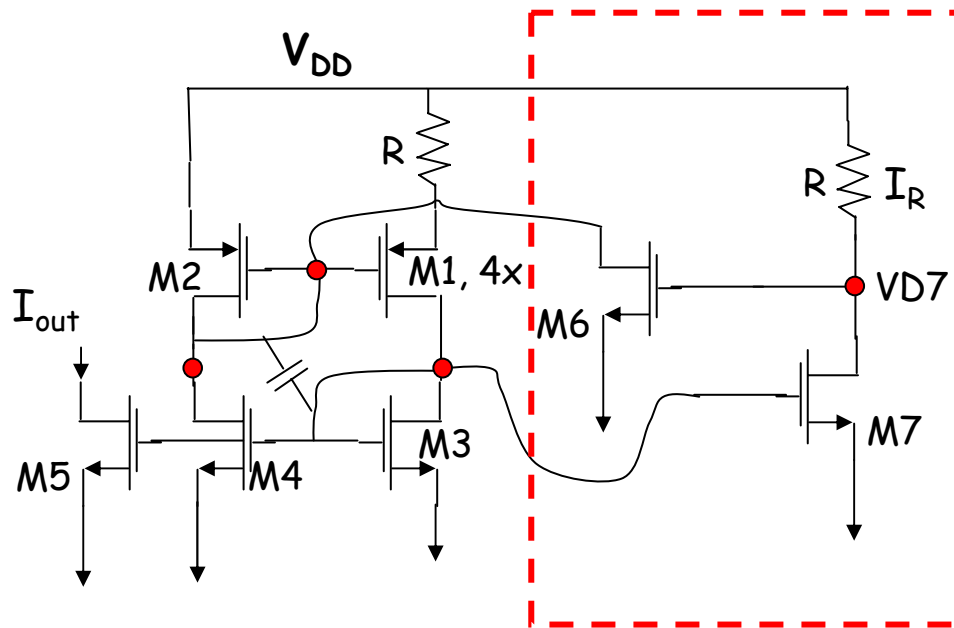
- The IPTAT current in Brokaw bandgap cell will be re-used
- The 10uA IPTAT is mirrored out to generate 10uA & 2.5uA current sinks.
- The critical point to watch is the slope of IPTAT and its T.C.
- For real applications, we want to match these numbers with those which need compensations.





Constant Gm current reference

Start-up Circuit



Adding a start - up circuit to make sure $I_{D2} \neq 0$

$$I_{D2} = \left[\frac{(W/L)_4}{(W/L)_3} \right]^2 \frac{(1 - \sqrt{\frac{(W/L)_2 (W/L)_3}{(W/L)_1 (W/L)_4}})^2}{\beta_2 R^2} \text{ 2nd solution}$$

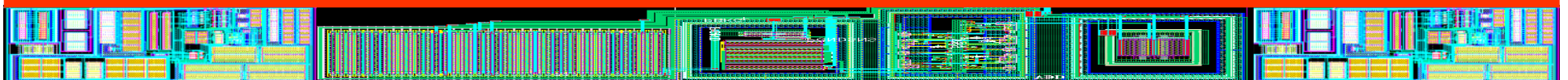
Choose $(W/L)_1 = 4x(W/L)_2$; $(W/L)_3 = (W/L)_4$

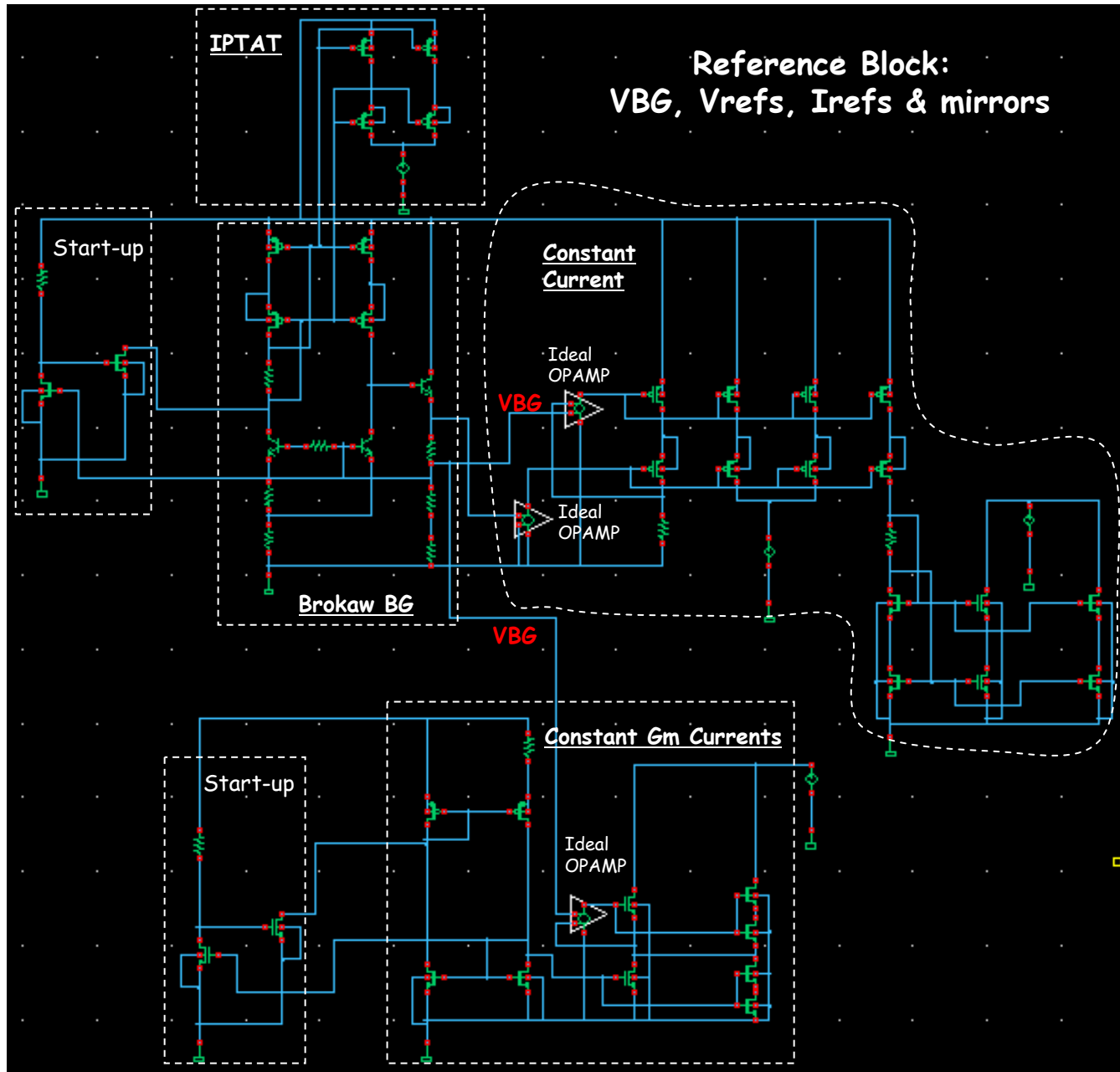
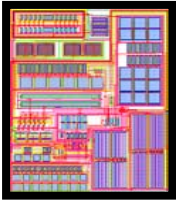
$$\text{Thus } I_{D2} = \frac{1}{2\beta_2 R^2} = 10\mu\text{A}; R = \sqrt{\frac{1}{2\beta_2 \times 10\mu\text{A}}}$$

Use dc sweep to estimate $\beta = \frac{1}{2} \mu C_{ox} \frac{W}{L}$ from $I_D = \beta V_{GS}^2$

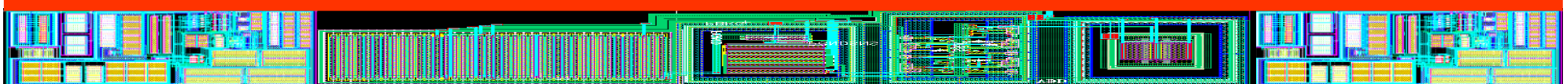
If M2's size is chosen first β is estimated. Then R can be estimated.

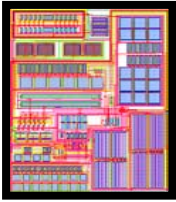
Let's try to construct the constant Gm cell with the estimate sizes.





UTD Models





Thermal Shut-Down Circuit

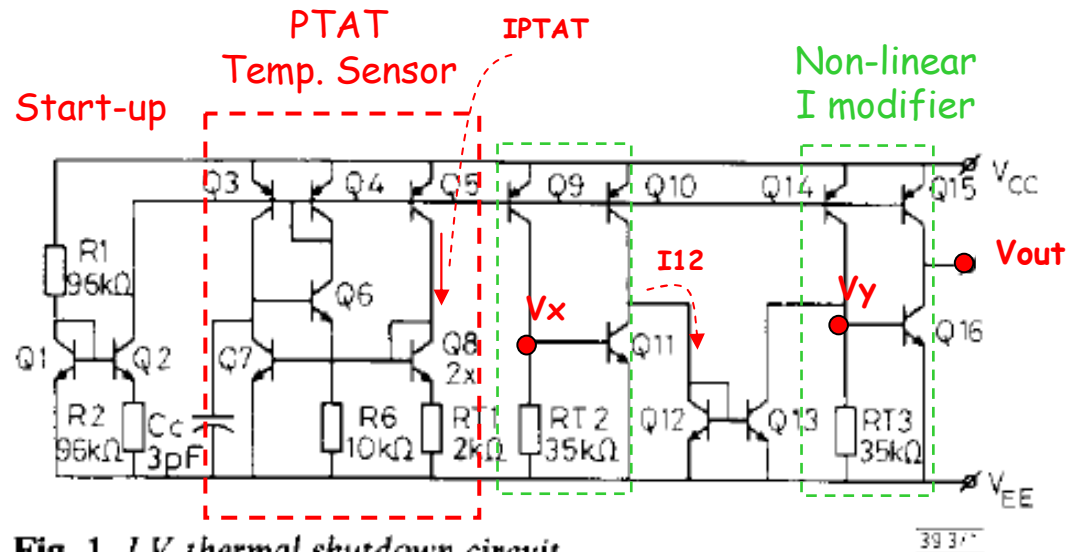
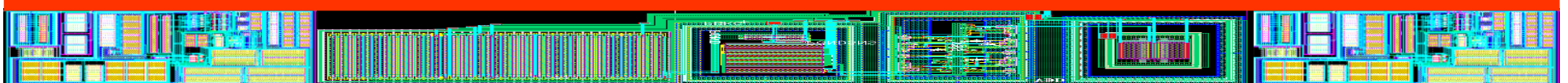
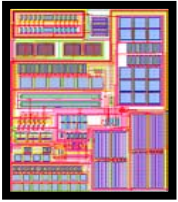


Fig. 1 1V thermal shutdown circuit

"Integrated 1V Thermal Shutdown Circuit", M.H. Nagel et al.,
IEEE Electronics Letters,
7th Mar 1992, Vol.28, No. 10, p.969.





Design procedure of Thermal Shut-Down Circuit

$$1) I_{PTAT} = \frac{kT \ln(n)}{qR_{T1}},$$

If set $n = 2$, $I_{PTAT} = 10\mu A$, get R_{T1} value

$$2) T_Z(K) \sim \frac{qV_{g0}}{k} \frac{1}{\frac{R_{T2}}{R_{T1}} - \ln \frac{I_{PTAT}}{2c_1}},$$

Where $V_{g0} = 1.176V$ is bandgap voltage of Silicon

at $0^\circ K$ &

c_1 is saturation current coefficient.

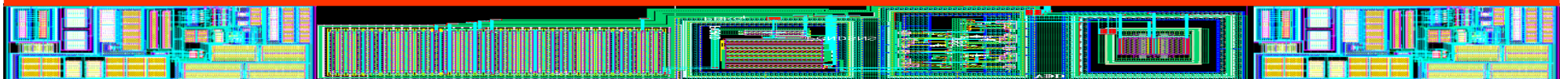
$c_1 \sim IPTAT/2e^{-6}$ (reverse engineering formula!)

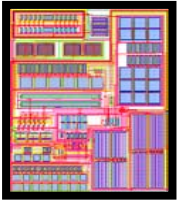
$T_{Z,H} = 150^\circ C$, from the above equation, get $R_{T2,H}$ value.

$T_{Z,L} = 130^\circ C$, get $R_{T2,L}$ value.

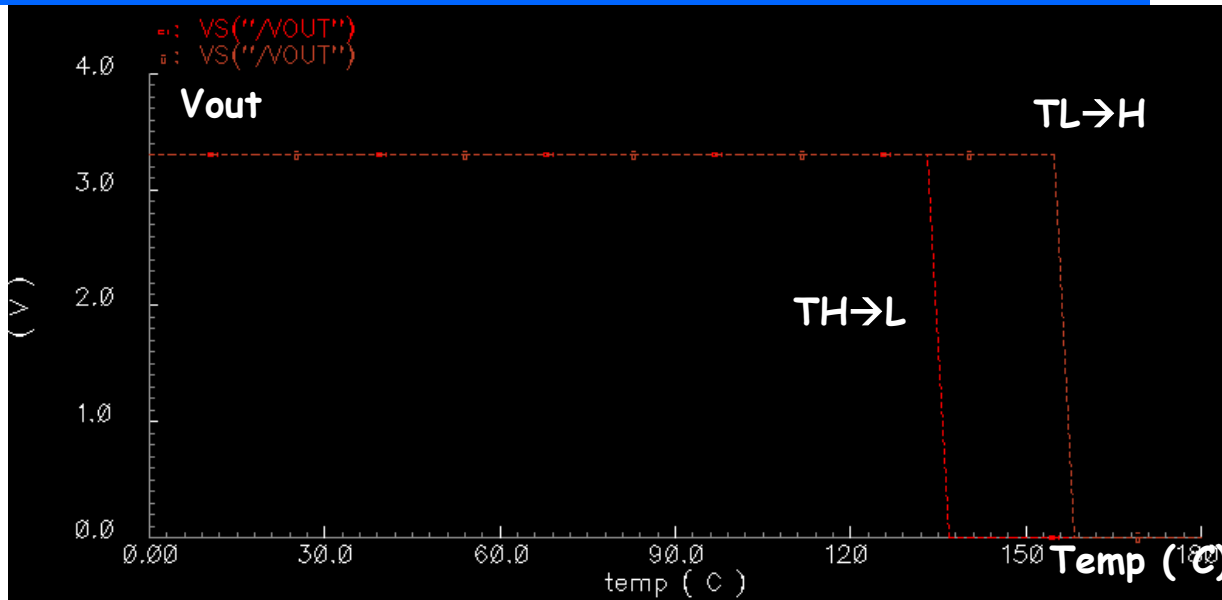
3) Please use a NMOS SW to change between $R_{T2,L}$ and $R_{T2,H}$ to get temp. hysteresis.

You will need to adjust $R_{T2,L}$ to get the right temp.

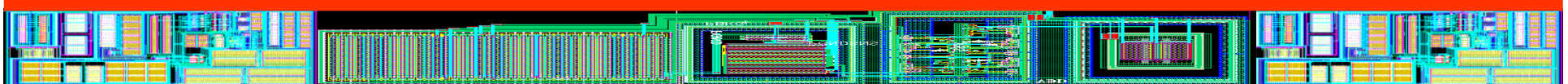
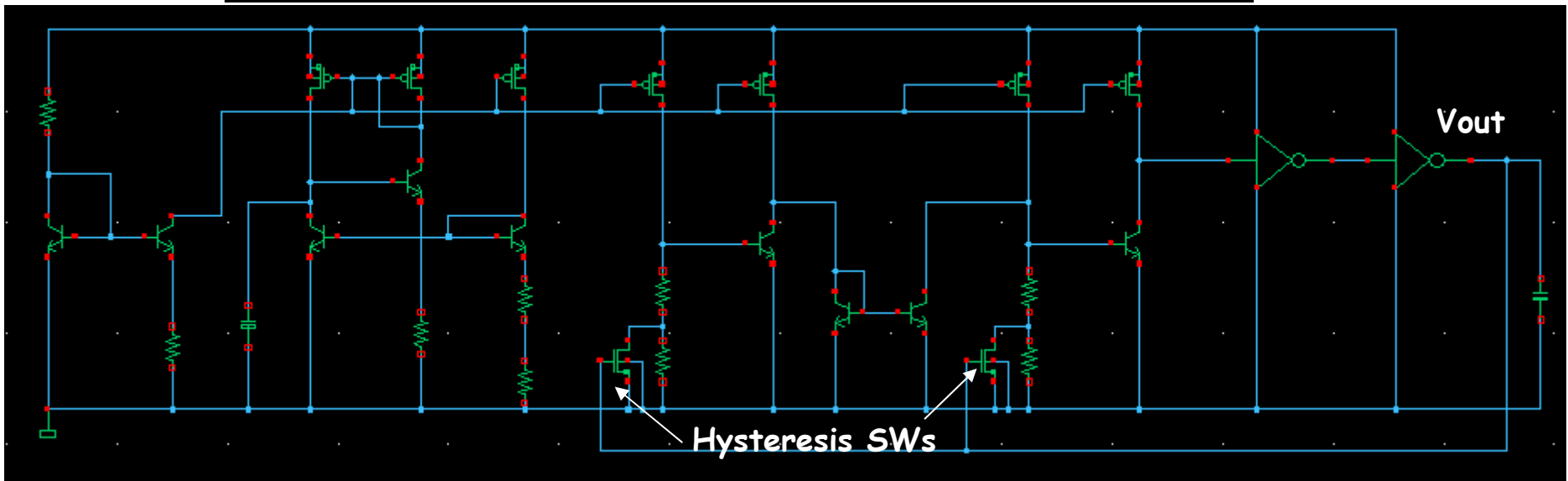


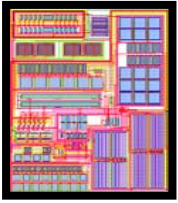


BiCMOS version of thermal shut down circuit



UTD Models





Summary

- The final design values should be reported based on simulation results. The values in this design guide is a good starting point.
- Good Luck!
- No late homework!
- Any HW related questions should be asked before the due date. Students are also encouraged to attend announced tutorial sessions and office hours. Any special request for additional meeting and questions raised after HW due date will be answered or arranged based on the availability of schedule.

